MULTIGIG RT | MULTIGIG RT 2

TE Internal #: 1410188-3

High Speed Backplane Connectors, 112 Position, Mating

Alignment, Polarization Mating Alignment Type, 7 Row, 16 Column,

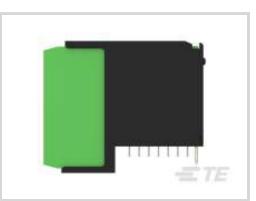
PCB Mount Header, MULTIGIG RT 2

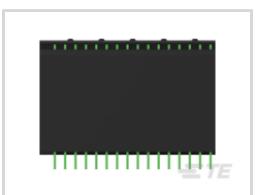
View on TE.com >

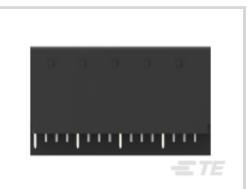


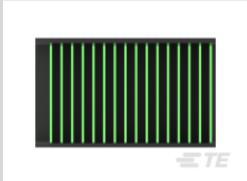
Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Connector System: Board-to-Board

Number of Positions: 112

Row-to-Row Spacing: 1.35 mm [.053 in]

Mating Alignment: With

Mating Alignment Type: Polarization

Features

Product Type Features

Applied to Printed Circuit Board Type	Daughtercard
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Fully Shrouded
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Card Slot Centerline	20.3 mm[.8 in]
Backplane Architecture	Traditional Backplane
Number of Positions	112
Number of Rows	7
Number of Columns	16
PCB Mount Orientation	Right Angle
Guide Location	Right

Contact Features



Contact Current Rating (Max)	1 A
Mechanical Attachment	
Mating Alignment	With
Mating Alignment Type	Polarization
Connector Mounting Type	Board Mount
Housing Features	
Number of Shrouded Sides	2
Centerline (Pitch)	1.8 mm[.071 in]
Dimensions	
Row-to-Row Spacing	1.35 mm[.053 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Power & Signal

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Pb (7% in contact plating) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
Solder Process Capability	Not applicable for solder process capability

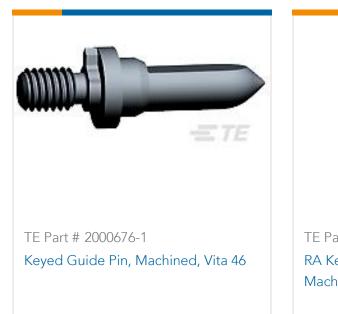
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products



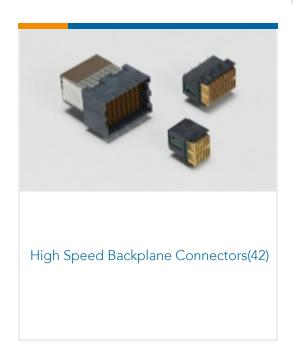
will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | MULTIGIG RT 2



Customers Also Bought





















Documents

Product Drawings

MULTIGIG RT T2 7RW DC DF F-RGT

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1410188-3_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1410188-3_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1410188-3_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

Board-Level Interconnects for Rugged Embedded Computing Brochure

English

Product Environmental Compliance

TE Material Declaration

English

Instruction Sheets

Instruction Sheet (U.S.)

English